FAIRCHILD SEMICONDUCTOR®

March 2013

FCA16N60N

N-Channel SupreMOS® MOSFET

600 V, 16 A, 199 mΩ

Features

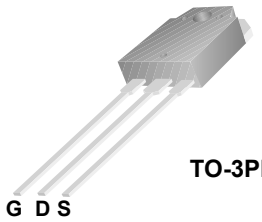
- $R_{DS(on)}$ = 170 mΩ (Typ.) @ V_{GS} = 10V, I_D = 8 A
- Ultra low gate charge (Typ. Q_g = 40.2 nC)
- Low effective output capacitance (Typ. C_{oss}.eff = 176 pF)
- 100% avalanche tested
- RoHS compliant

Application

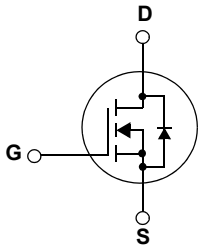
- PDP TV
- AC-DC Power Supply

Description

The SupreMOS® MOSFET is Fairchild Semiconductor®'s next generation of high voltage super-junction (SJ) technology employing a deep trench filling process that differentiates it from the conventional SJ MOSFETs. This advanced technology and precise process control provides lowest Rsp on-resistance, superior switching performance and ruggedness. SupreMOS MOSFET is suitable for high frequency switching power converter applications such as PFC, server/telecom power, FPD TV power, ATX power and industrial power applications.



TO-3PN



MOSFET Maximum Ratings T_C = 25°C unless otherwise noted*

Symbol	Parameter		FCA16N60N	Unit
V_{DSS}	Drain to Source Voltage		600	V
V_{GSS}	Gate to Source Voltage		±30	V
I_D	Drain Current	-Continuous (T_C = 25°C)	16.0	A
		-Continuous (T_C = 100°C)	10.1	
I_{DM}	Drain Current	- Pulsed (Note 1)	48.0	A
E_{AS}	Single Pulsed Avalanche Energy	(Note 2)	355	mJ
I_{AR}	Avalanche Current		5.3	A
E_{AR}	Repetitive Avalanche Energy		1.34	mJ
dv/dt	MOSFET dv/dt Ruggedness		100	V/ns
	Peak Diode Recovery dv/dt	(Note 3)	20	V/ns
P_D	Power Dissipation	(T_C = 25°C)	134.4	W
		- Derate above 25°C	1.08	W/°C
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150	°C
T_L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds		300	°C

*Drain current limited by maximum junction temperature

Thermal Characteristics

Symbol	Parameter	FCA16N60N	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.93	°C/W
$R_{\theta CS}$	Thermal Resistance, Case to Heat Sink (Typical)	0.24	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	40	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FCA16N60N	FCA16N60N	TO-3PN	-	-	30

Electrical Characteristics $T_C = 25^oC$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
BV_{DSS}	Drain to Source Breakdown Voltage	I_D = 1 mA, V_{GS} = 0 V, $T_C = 25^oC$	600	-	-	V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I_D = 1 mA, Referenced to 25^oC	-	0.73	-	$V/^oC$
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 480 V, V_{GS} = 0 V	-	-	10	μA
		V_{DS} = 480 V, V_{GS} = 0 V, $T_C = 125^oC$	-	-	100	
I_{GSS}	Gate to Body Leakage Current	V_{GS} = ±30 V, V_{DS} = 0 V	-	-	±100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}$, I_D = 250 μA	2.0	-	4.0	V
$R_{DS(on)}$	Static Drain to Source On Resistance	V_{GS} = 10 V, I_D = 8 A	-	0.170	0.199	Ω
g_{FS}	Forward Transconductance	V_{DS} = 40 V, I_D = 8 A	-	20	-	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS} = 100 V, V_{GS} = 0 V, f = 1 MHz	-	1630	2170	pF
C_{oss}	Output Capacitance		-	70	95	pF
C_{rss}	Reverse Transfer Capacitance		-	5	10	pF
C_{oss}	Output Capacitance	V_{DS} = 380 V, V_{GS} = 0 V, f = 1 MHz	-	40	60	pF
C_{oss}eff.	Effective Output Capacitance	V_{DS} = 0 V to 480 V, V_{GS} = 0 V	-	176	-	pF
$Q_{g(tot)}$	Total Gate Charge at 10V	V_{DS} = 380 V, I_D = 8 A, V_{GS} = 10 V (Note 4)	-	40.2	52.3	nC
Q_{gs}	Gate to Source Gate Charge		-	6.7	-	nC
Q_{gd}	Gate to Drain “Miller” Charge		-	12.9	-	nC
ESR	Equivalent Series Resistance (G-S)	Drain Open		2.9		Ω
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	V_{DD} = 380 V, I_D = 8 A, R_G = 4.7 Ω (Note 4)	-	15.8	41.6	ns
t_r	Turn-On Rise Time		-	15.5	41.0	ns
$t_{d(off)}$	Turn-Off Delay Time		-	60.3	130.6	ns
t_f	Turn-Off Fall Time		-	20.2	50.4	ns
Drain-Source Diode Characteristics						
I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	16	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	48	A
V_{SD}	Drain to Source Diode Forward Voltage	V_{GS} = 0 V, I_{SD} = 8 A	-	-	1.2	V
t_{rr}	Reverse Recovery Time	V_{GS} = 0 V, I_{SD} = 8 A, dI_F/dt = 100 A/μs	-	319	-	ns
Q_{rr}	Reverse Recovery Charge		-	4.4	-	μC

Notes:
1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. I_{AS} = 5.3 A, R_G = 25 Ω, Starting T_J = 25°C
3. $I_{SD} \le$ 16 A, di/dt ≤ 200 A/μs, V_{DD} = 380 V, Starting T_J = 25°C
4. Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

Figure 1. On-Region Characteristics

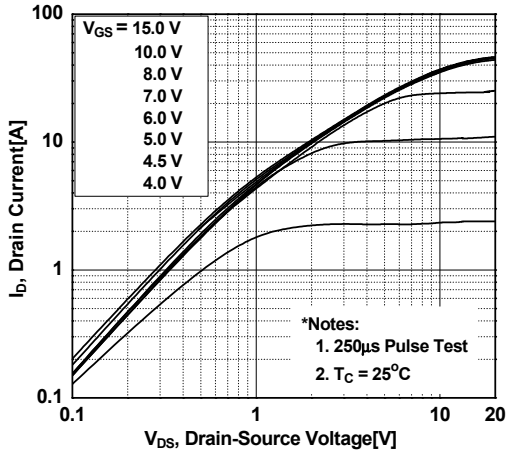


Figure 2. Transfer Characteristics

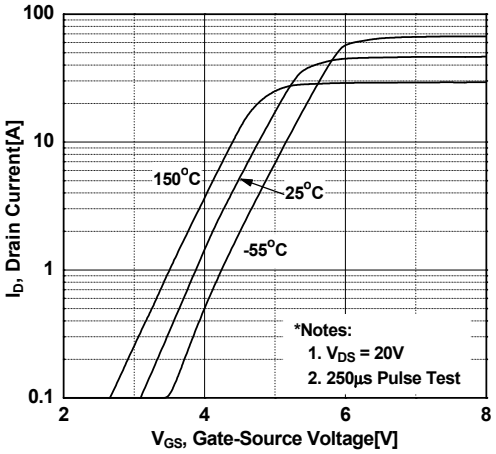


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

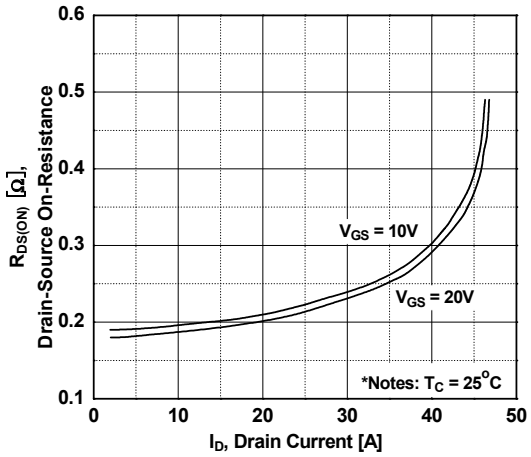


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

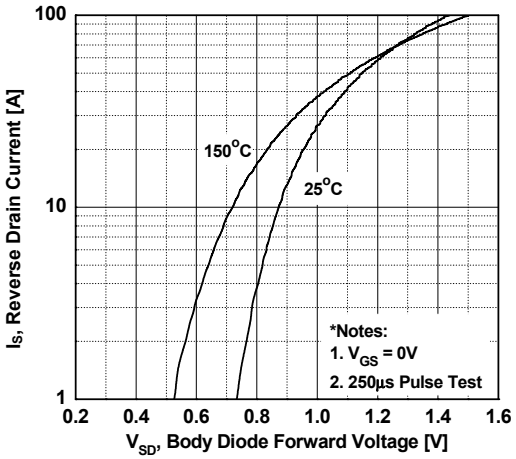


Figure 5. Capacitance Characteristics

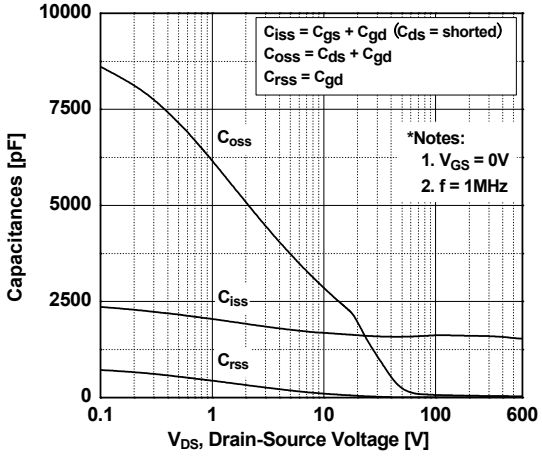
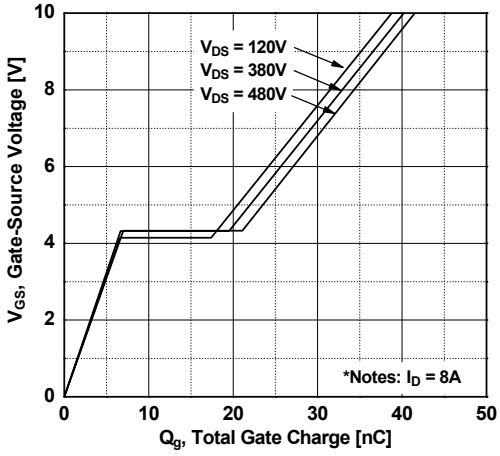


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

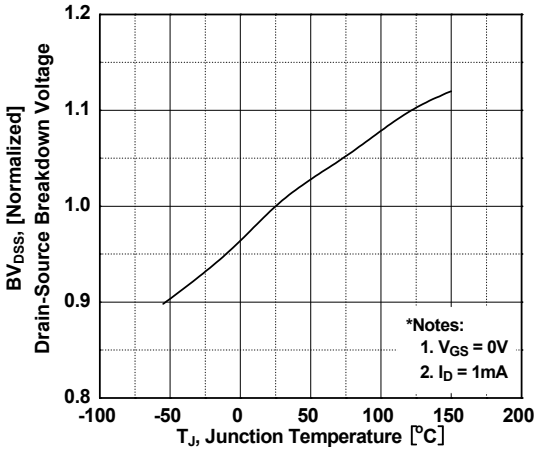


Figure 8. On-Resistance Variation vs. Temperature

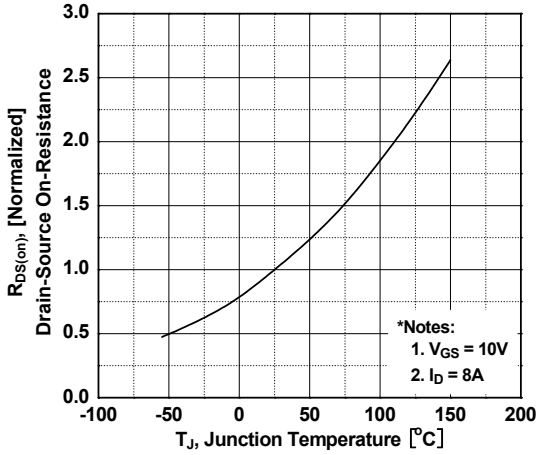


Figure 9. Maximum Safe Operating Area

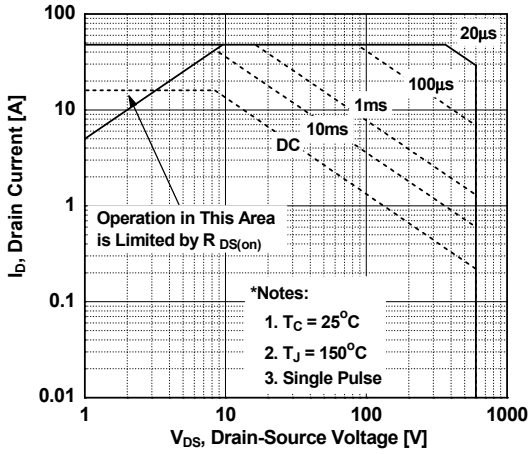


Figure 10. Maximum Drain Current vs. Case Temperature

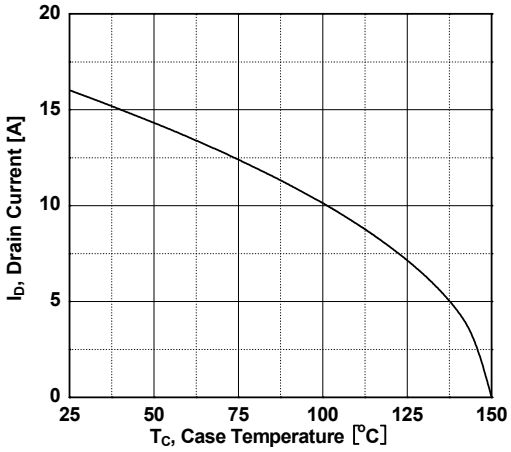
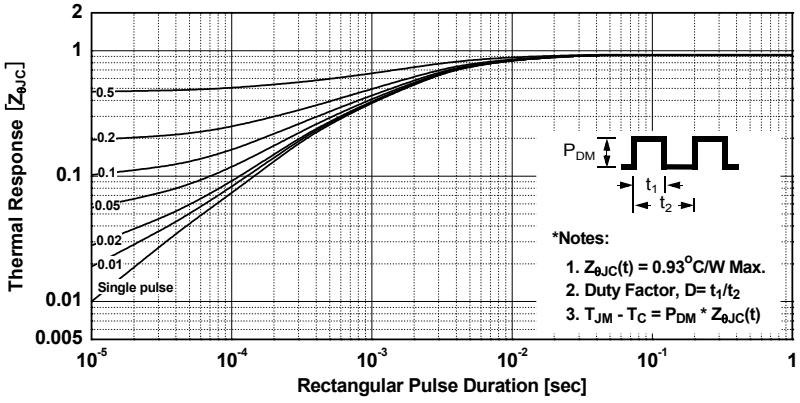
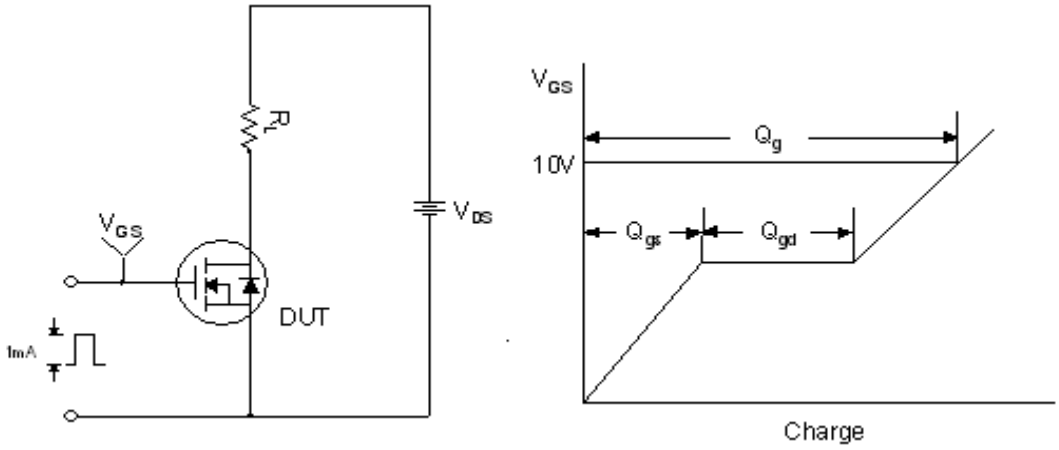


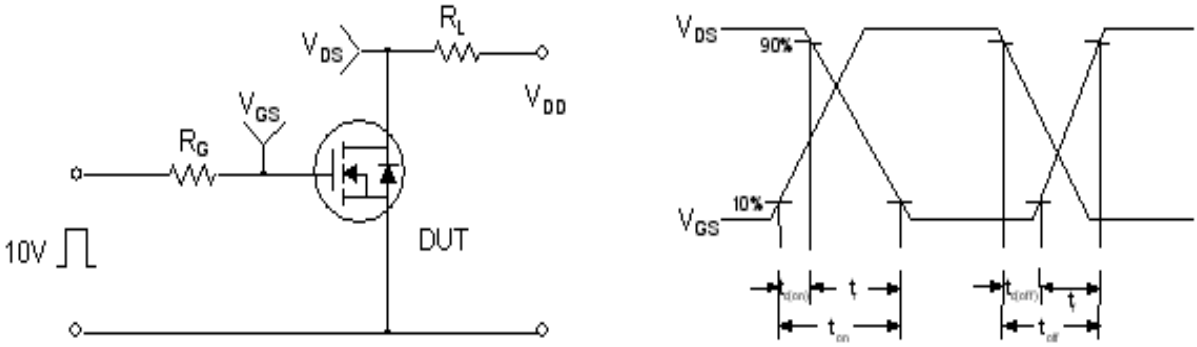
Figure 11. Transient Thermal Response Curve



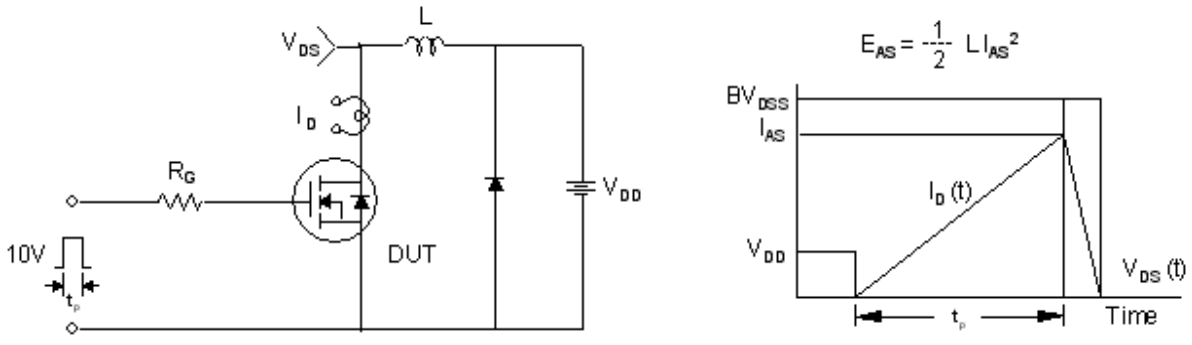
Gate Charge Test Circuit & Waveform



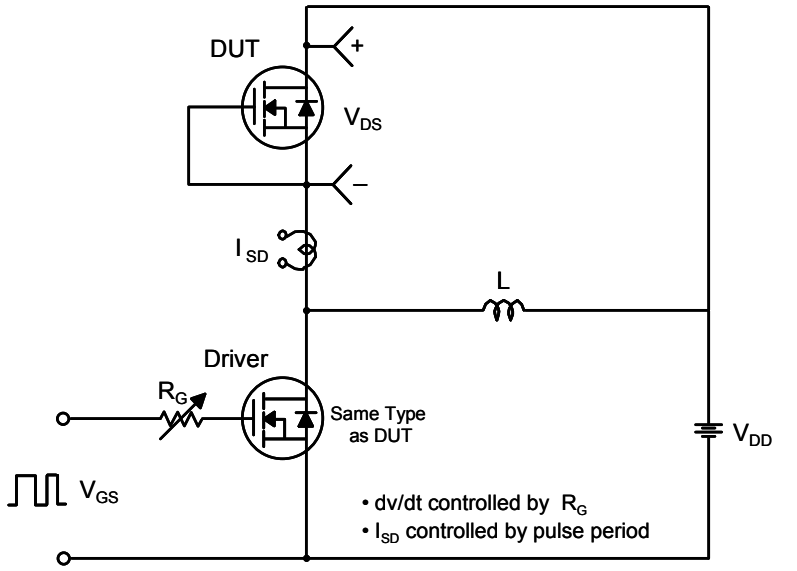
Resistive Switching Test Circuit & Waveforms

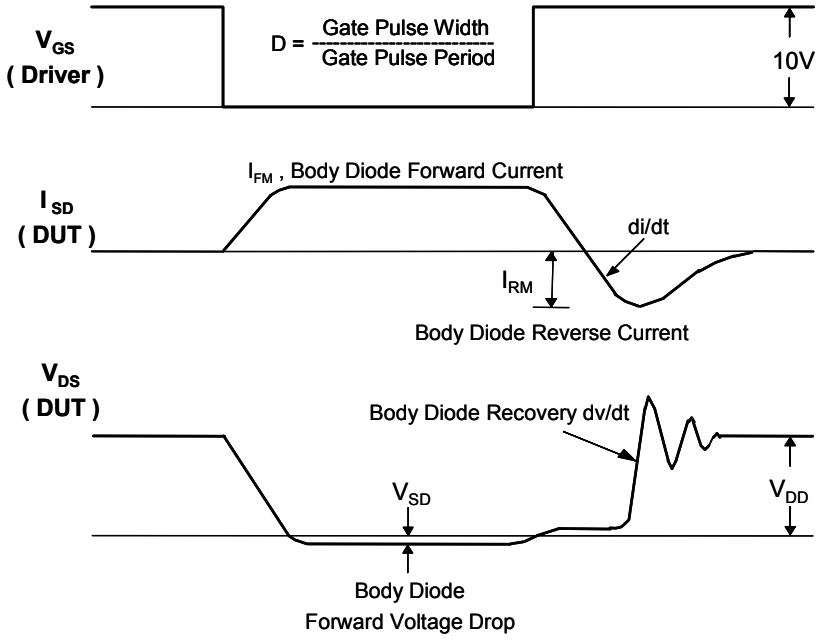


Unclamped Inductive Switching Test Circuit & Waveforms



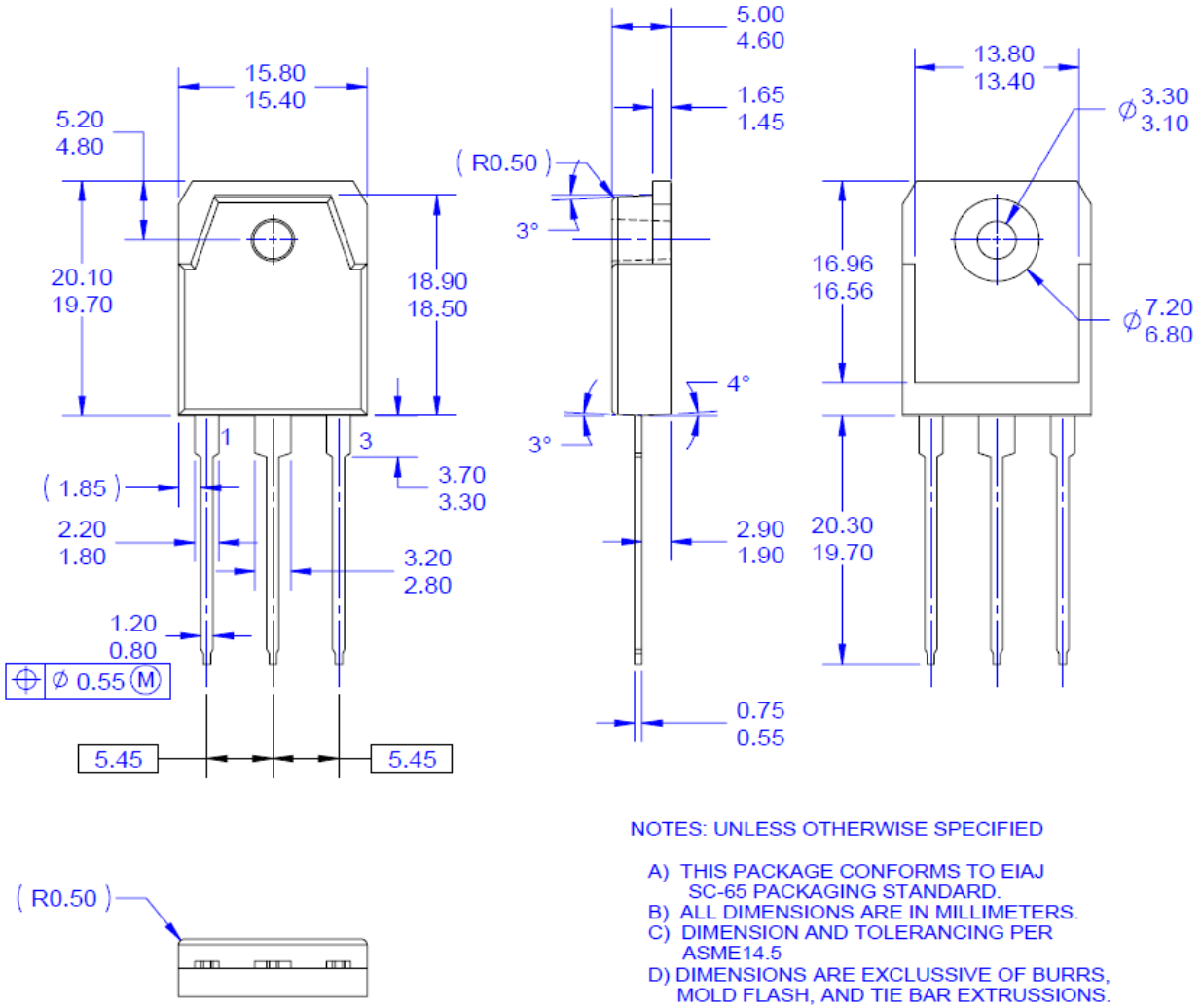
Peak Diode Recovery dv/dt Test Circuit & Waveforms





Mechanical Dimensions

TO-3PN



NOTES: UNLESS OTHERWISE SPECIFIED

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B) ALL DIMENSIONS ARE IN MILLIMETERS.
C) DIMENSION AND TOLERANCING PER ASME14.5
D) DIMENSIONS ARE EXCLUSSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSSIONS.
E) THIS PACKAGE IS INTENDED ONLY FOR TO3PN.
F) DRAWING FILE NAME: TO3P03AREV4.

Dimensions in Millimeters

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Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
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